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Fundamentals of Microsystems Packaging (EPI), Tummala, Rao ...

Microsystems packaging involves two major zones: one is the device (IC) zone, named „IC packaging“, and the other is the system-level, named „system packaging“, as shown in figure 1.2.1. Fig. 1.2.1 IC and system packaging The IC level involves interconnecting, powering, cooling and protecting the IC.

1. Fundamentals of microsystems packaging

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Chapter 1: Introduction to Microsystems Packaging ...

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